

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

**FEATURES**

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals

**MECHANICAL DATA**

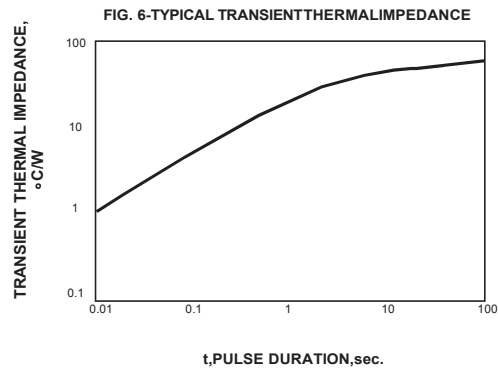
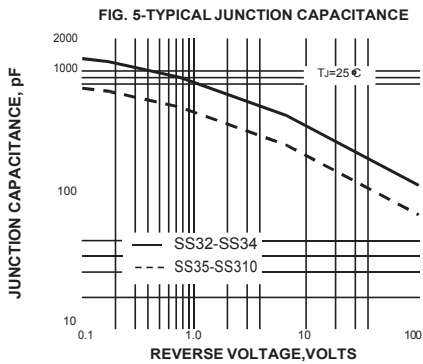
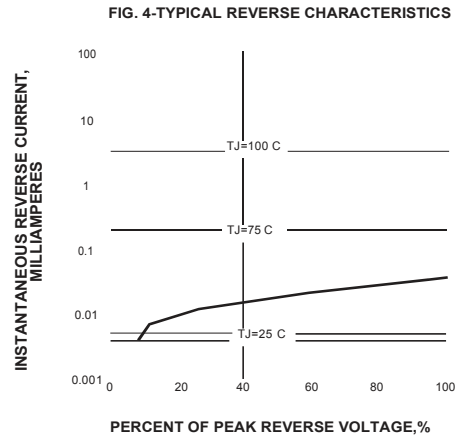
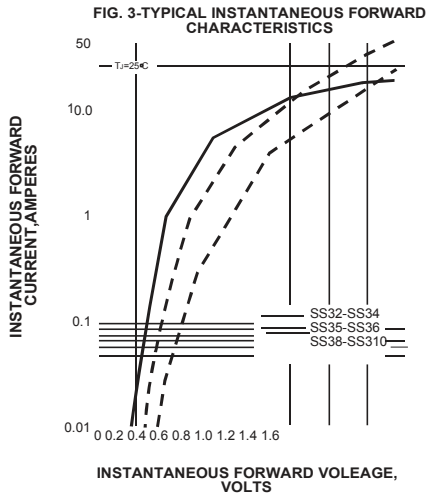
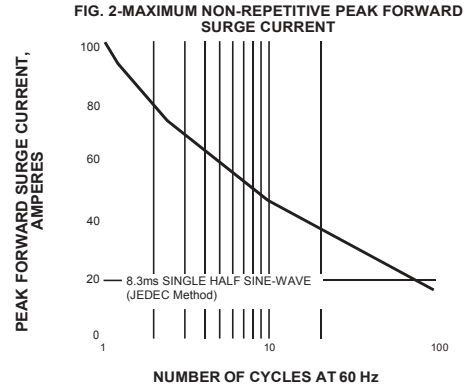
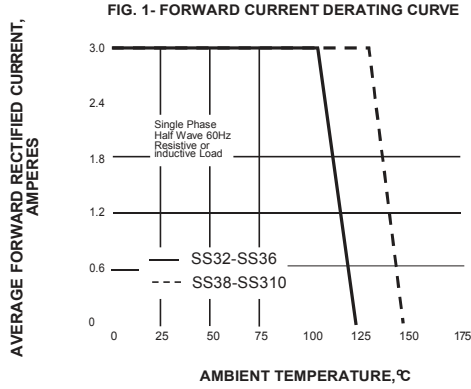
**Case:** DO-214AC  
**Terminals:** leads solderable per MIL-STD-750, Method 2026  
**Polarity:** Color band denotes cathode end  
**Mounting Position:** Any  
**Weight:** 0.002 ounce, 0.07 grams

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

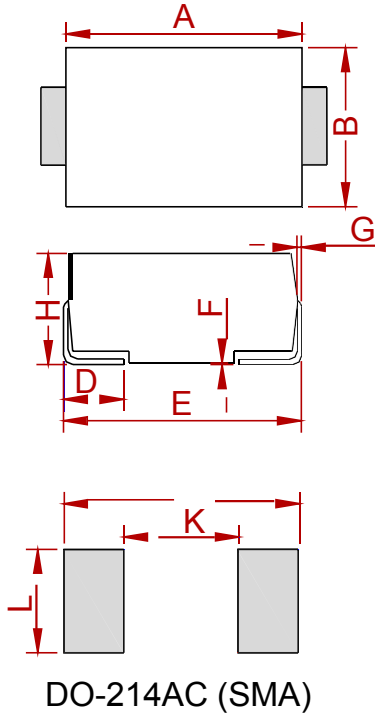
Ratings at 25°C ambient temperature unless otherwise specified.  
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	SS32-MS	SS34-MS	SS36-MS	SS310-MS	UNITS
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	20	40	60	100	VOLTS
Maximum RMS voltage	V <sub>RMS</sub>	14	28	42	70	VOLTS
Maximum DC blocking voltage	V <sub>DC</sub>	20	40	60	100	VOLTS
Maximum average forward rectified current at T <sub>L</sub> (see fig. 1)	I <sub>(AV)</sub>	3.0				Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	100.0				Amps
Maximum instantaneous forward voltage at 3.0A	V <sub>F</sub>	0.55	0.70	0.85		Volts
Maximum DC reverse current at rated DC blocking voltage	I <sub>R</sub>	0.5				mA
TA=25°C TA=100°C		20		10		
Typical junction capacitance (NOTE 1)	C <sub>J</sub>	500	300			pF
Typical thermal resistance (NOTE 2)	R <sub>θJA</sub>	55.0				C/W
Operating junction temperature range	T <sub>J</sub>	-50 to +125			-50 to +150	°C
Storage temperature range	T <sub>STG</sub>	-50 to +150				°C

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 2. P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas



**PACKAGE MECHANICAL DATA**



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

**REEL SPECIFICATION**

P/N	PKG	QTY
SS32-MS THRU SS310-MS	SMA	2000

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